

Product / Package Information

| | |
|-----------------|---------------|
| Package | LQFP |
| Body Size (mm) | 14 X 20 X 1.4 |
| Lead Count | 128 |
| Terminal Finish | 100 Sn |

Environmental Information

| | |
|----------------------------|-----|
| RoHS Compliant | Yes |
| High Temperature Compliant | Yes |
| Halogen Free Compliant | Yes |
| REACH SVHC Compliant | Yes |

Materials Declaration

Molding Compound

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------------|----------------------|-------------|------------|----------------------------|---------|-----------------|--------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Silica | 60676-86-0 | 5.98E-01 | 88.0 | 880000 | 63.62 | 636238 |
| Thermosets | Epoxy & Phenol resin | Proprietary | 7.81E-02 | 11.5 | 115000 | 8.31 | 83145 |
| Other inorganic materials | Carbon black | 1333-86-4 | 3.40E-03 | 0.5 | 5000 | 0.36 | 3615 |
| Subtotal | | | 6.79 E-01 | 100.00 | 1000000 | 72.30 | 722997 |

Leadframe

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------|-----------|-----------|------------|----------------------------|---------|-----------------|--------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Copper & its alloys | Copper | 7440-50-8 | 1.97E-01 | 96.20 | 962000 | 20.94 | 209359 |
| Copper & its alloys | Nickel | 7440-02-0 | 6.14E-03 | 3.00 | 30000 | 0.65 | 6529 |
| Copper & its alloys | Silicon | 7440-21-3 | 1.33E-03 | 0.65 | 6500 | 0.14 | 1415 |
| Copper & its alloys | Magnesium | 7439-95-4 | 3.07E-04 | 0.15 | 1500 | 0.03 | 326 |
| Subtotal | | | 2.05 E-01 | 100.00 | 1000000 | 21.76 | 217629 |

Internal Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|-----------------|-----------|-----------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious Metals | Silver | 7440-22-4 | 3.61 E-03 | 100.0 | 1000000 | 0.38 | 3841 |

External Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|------------------|-----------|-----------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Tin & its alloys | Tin | 7440-31-5 | 6.98 E-03 | 100.0 | 1000000 | 0.74 | 7427 |

Bond Wires

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|-----------------|-----------|-----------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious Metals | Gold | 7440-57-5 | 6.16 E-03 | 100.00 | 1000000 | 0.66 | 6555 |

Chip

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------------|---------------|-----------|------------|----------------------------|---------|-----------------|-------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Doped Silicon | 7440-21-3 | 3.44 E-02 | 100.0 | 1000000 | 3.66 | 36603 |

Die Attach

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|-------------------------|-------------------------|-------------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious Metals | Silver | 7440-22-4 | 3.51E-03 | 75.47 | 754700 | 0.37 | 3734 |
| Other organic materials | Epoxy resin | Proprietary | 8.77E-04 | 18.87 | 188700 | 0.09 | 934 |
| Other organic materials | Gamma Butyrolactone | 96-48-0 | 1.32E-04 | 2.83 | 28300 | 0.01 | 140 |
| Others | Curing agent & hardener | Proprietary | 1.32E-04 | 2.83 | 28300 | 0.01 | 140 |
| Subtotal | Subtotal | | 4.65 E-03 | 100.00 | 1000000 | 0.49 | 4948 |

| | | | | | | | |
|-----------------------|--|--|--------------------------------|--|--|---------------------------------|-----------------------|
| Package Totals | | | Weight (g) 9.40 E-01 | | | Percentage (%) 100.00 | PPM 1000000 |
|-----------------------|--|--|--------------------------------|--|--|---------------------------------|-----------------------|

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

Product / Package Information

| | |
|-----------------|---------------|
| Package | LQFP |
| Body Size (mm) | 14 X 20 X 1.4 |
| Lead Count | 128 |
| Terminal Finish | SnPb |

Environmental Information

| | |
|----------------------------|-----|
| RoHS Compliant | No |
| High Temperature Compliant | No |
| Halogen Free Compliant | Yes |
| REACH SVHC Compliant | Yes |

Materials Declaration

Molding Compound

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------------|----------------------|-------------|------------|----------------------------|---------|-----------------|--------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Silica | 60676-86-0 | 5.98E-01 | 88.0 | 880000 | 63.62 | 636238 |
| Thermosets | Epoxy & Phenol resin | Proprietary | 7.81E-02 | 11.5 | 115000 | 8.31 | 83145 |
| Other inorganic materials | Carbon black | 1333-86-4 | 3.40E-03 | 0.5 | 5000 | 0.36 | 3615 |
| Subtotal | | | 6.79 E-01 | 100.00 | 1000000 | 72.30 | 722997 |

Leadframe

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------|-----------|-----------|------------|----------------------------|---------|-----------------|--------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Copper & its alloys | Copper | 7440-50-8 | 1.97E-01 | 96.20 | 962000 | 20.94 | 209359 |
| Copper & its alloys | Nickel | 7440-02-0 | 6.14E-03 | 3.00 | 30000 | 0.65 | 6529 |
| Copper & its alloys | Silicon | 7440-21-3 | 1.33E-03 | 0.65 | 6500 | 0.14 | 1415 |
| Copper & its alloys | Magnesium | 7439-95-4 | 3.07E-04 | 0.15 | 1500 | 0.03 | 326 |
| Subtotal | | | 2.05 E-01 | 100.00 | 1000000 | 21.76 | 217629 |

Internal Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|-----------------|-----------|-----------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious Metals | Silver | 7440-22-4 | 3.61 E-03 | 100.0 | 1000000 | 0.38 | 3841 |

External Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|------------------|-----------|-----------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Tin & its alloys | Tin | 7440-31-5 | 5.93E-03 | 85.0 | 850000 | 0.63 | 6313 |
| Tin & its alloys | Lead | 7439-92-1 | 1.05E-03 | 15.0 | 150000 | 0.11 | 1114 |
| Subtotal | | | 6.98 E-03 | 100.0 | 1000000 | 0.74 | 7427 |

Bond Wires

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|-----------------|-----------|-----------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious Metals | Gold | 7440-57-5 | 6.16 E-03 | 100.00 | 1000000 | 0.66 | 6555 |

Chip

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------------|---------------|-----------|------------|----------------------------|---------|-----------------|-------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Doped Silicon | 7440-21-3 | 3.44 E-02 | 100.0 | 1000000 | 3.66 | 36603 |

Die Attach

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|-------------------------|-------------------------|-------------|------------|----------------------------|---------|-----------------|------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious Metals | Silver | 7440-22-4 | 3.51E-03 | 75.47 | 754700 | 0.37 | 3734 |
| Other organic materials | Epoxy resin | Proprietary | 8.77E-04 | 18.87 | 188700 | 0.09 | 934 |
| Other organic materials | Gamma Butyrolactone | 96-48-0 | 1.32E-04 | 2.83 | 28300 | 0.01 | 140 |
| Others | Curing agent & hardener | Proprietary | 1.32E-04 | 2.83 | 28300 | 0.01 | 140 |
| Subtotal | Subtotal | | 4.65 E-03 | 100.00 | 1000000 | 0.49 | 4948 |

| | | | | | | | |
|-----------------------|--|--|--------------------------------|--|--|---------------------------------|-----------------------|
| Package Totals | | | Weight (g) 9.40 E-01 | | | Percentage (%) 100.00 | PPM 1000000 |
|-----------------------|--|--|--------------------------------|--|--|---------------------------------|-----------------------|

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ADI Proprietary